# FP1007R6

## High frequency, high current power inductors



#### **Product features**

- 10.5 x 8.0 x 7.0mm Maximum surface mount package
- Ferrite core material
- Controlled DCR tolerance for sensing circuits
- Inductance Range from 150nH to 470nH
- Current range from 23.5 to 75 Amps
- Frequency range up to 2MHz
- · Halogen free, lead free, RoHS compliant

#### **Applications**

- Multi-phase regulators
- Voltage Regulator Modules (VRMs)
- Desktop and server VRMs and EVRDs
- Data networking and storage systems
- · Graphics cards and battery power systems
- Point-of-Load modules
- DCR Sensing

#### **Environmental data**

- Storage temperature range (component):
  -40 °C to +125 °C
- Operating temperature range: -40 °C to +125 °C (ambient plus self-temperature rise)
- Solder reflow temperature:
  J-STD-020 (latest revision) compliant







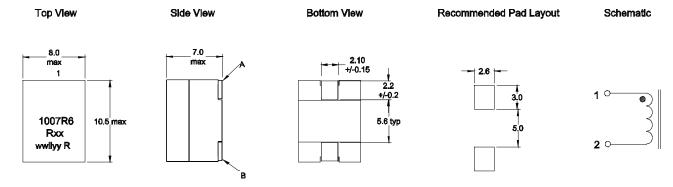


Product Specifications							
Part	OCL 1 ±10%	FLL <sup>2</sup> Min.	I <sub>rms</sub> <sup>3</sup>	I <sub>sat</sub> 1 <sup>4</sup> @25°C	I <sub>sat</sub> 2 <sup>5</sup> @100°C	DCR @20°C	
Number <sup>7</sup>	(nH)	(nH)	(Amps)	(Amps)	(Amps)	(mΩ)	K-Factor 6
FP1007R6-R15-R	150	108		75.0	60.0		
FP1007R6-R18-R	180	129		60.0	50.0		
FP1007R6-R22-R	220	158		50.0	40.0		
FP1007R6-R27-R	270	194	61	41.0	33.0	0.29 ± 5%	348.8
FP1007R6-R33-R	330	237		33.0	26.5		
FP1007R6-R39-R	390	280		28.0	22.5		
FP1007R6-R47-R	470	338	1	23.5	19.0		

- 1. Open Circuit Inductance (OCL) Test Parameters: 100kHz, 0.10Vrms, 0.0Adc
- 2. Full Load Inductance (FLL) Test Parameters: 100kHz, 0.1 $V_{rms}$ ,  $I_{sat1}$
- 3. I<sub>rms</sub>: DC current for an approximate temperature rise of 40°C without core loss. Derating is necessary for AC currents. PCB layout, trace thickness and width, air-flow, and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.
- 4. I<sub>Sat</sub>1: Peak current for approximately 20% rolloff at +25°C.

- 5. I<sub>Sat2</sub>: Peak current for approximately 20% rolloff at +100°C.
- 6. K-factor: Used to determine Bp-p for core loss (see graph). Bp-p = K  $^{\star}$  L
- $^*$   $\Delta l$  \*  $10^{-3}$  .  $B_{p\text{-}p\text{:}}(Gauss),$  K: (K-factor from table), L: (Inductance in nH),  $\Delta l$  (peak-to-peak ripple current in Amps).
- 7. Part Number Definition: FP1007R6-Rxx-R FP1007R6 = Product code and size Rxx= Inductance value in uH, R = decimal point -R suffix = RoHS compliant

#### **Dimensions- mm**



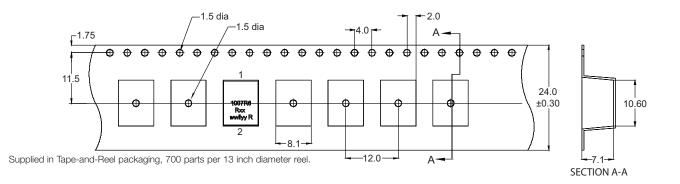
The nominal DCR is measured from point "A" to point "B"

Part Marking: 1007R6, Rxx = Inductance value in  $\mu$ H. (R = Decimal point) wwllyy = Date code R = Revision level Tolerance are  $\pm 0.15$ mm unless otherwise specified.

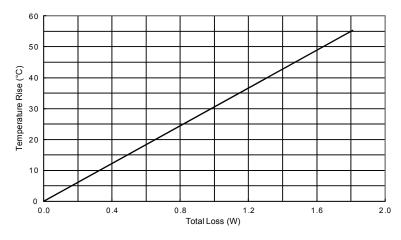
Soldering surfaces to be coplanar within 0.1016mm.

PCB tolerance  $\pm 0.1 \text{mm}$  unless otherwise specified.

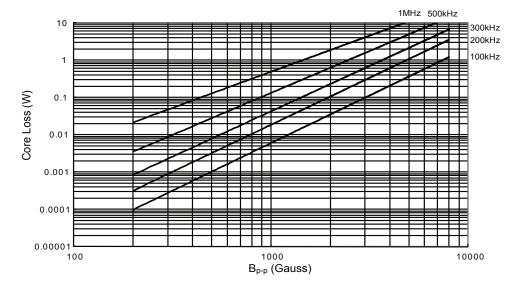
#### Packaging information - mm



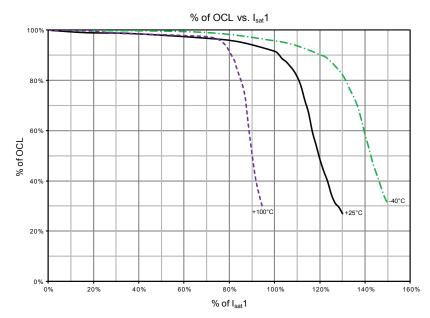
### Temperature rise vs total loss



#### Core loss vs Bp-p



#### **Inductance characteristics**



#### **Solder Reflow Profile**

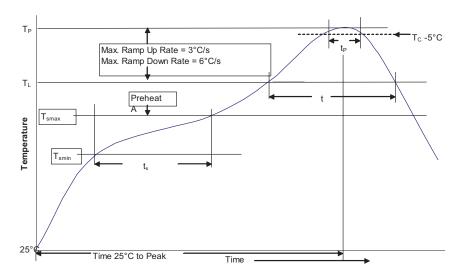


Table 1 - Standard SnPb Solder (T<sub>c</sub>)

		Volume	Volume
Pac	ckage	mm³	mm³
Th	nickness	<350	≥350
<	2.5mm	235°C	220°C
_≥′	2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (Tc)

Package	Volume mm³	Volume mm³	Volume mm³
Thickness	<350	350 - 2000	>2000
<1.6mm	260°C	260°C	260°C
1.6 - 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

#### Reference JDEC J-STD-020

Profile Feature		Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak	• Temperature min. (T <sub>smin</sub> )	100°C	150°C
	Temperature max. (T <sub>smax</sub> )	150°C	200°C
	• Time (T <sub>smin</sub> to T <sub>smax</sub> ) (t <sub>s</sub> )	60-120 Seconds	60-120 Seconds
Average ramp up rate T <sub>smax</sub> to T <sub>p</sub>		3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (TL)		183°C	217°C
Time at liquidous (t <sub>L</sub> )		60-150 Seconds	60-150 Seconds
Peak package body temperature (Tp)*		Table 1	Table 2
Time $(t_p)^{**}$ within 5 °C of the specified classification temperature $(T_c)$		20 Seconds**	30 Seconds**
Average ramp-down rate (T <sub>p</sub> to T <sub>smax</sub> )		6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature		6 Minutes Max.	8 Minutes Max.

 $<sup>^{\</sup>star}$  Tolerance for peak profile temperature (Tp) is defined as a supplier minimum and a user maximum.

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<sup>\*\*</sup> Tolerance for time at peak profile temperature  $(t_p)$  is defined as a supplier minimum and a user maximum.